



Material Content Data Sheet



Sales Product Name		IR38263MTRPBF		Issued		22. January 2018		
MA#		MA001688598						
Package		PG-IQFN-34-900		Weight*		115.24 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.349	1.17	1.17	11703	11703
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		113	
	non noble metal	zinc	7440-66-6	0.052	0.05		452	
	non noble metal	iron	7439-89-6	1.043	0.90		9047	
wire	non noble metal	copper	7440-50-8	42.333	36.73	37.69	367345	376957
	noble metal	gold	7440-57-5	0.504	0.44	0.44	4376	4376
	encapsulation	organic material	carbon black	1333-86-4	0.111	0.10		963
encapsulation	plastics	epoxy resin	-	5.713	4.96		49573	
	inorganic material	silicondioxide	60676-86-0	49.640	43.09	48.15	430753	481289
	leadfinish	noble metal	palladium	7440-05-3	0.001	0.00		12
plating	noble metal	gold	7440-57-5	0.002	0.00		19	
	non noble metal	nickel	7440-02-0	0.041	0.04	0.04	354	385
	noble metal	palladium	7440-05-3	0.001	0.00		12	
solder	noble metal	gold	7440-57-5	0.002	0.00		20	
	non noble metal	nickel	7440-02-0	0.042	0.04		366	
	noble metal	silver	7440-22-4	0.604	0.52	0.56	5240	5638
solder	noble metal	silver	7440-22-4	0.051	0.04		440	
	non noble metal	tin	7440-31-5	0.101	0.09		880	
	non noble metal	lead	7439-92-1	1.877	1.63	1.76	16284	17604
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.004	0.00		31	
	non noble metal	zinc	7440-66-6	0.014	0.01		122	
	non noble metal	iron	7439-89-6	0.282	0.24		2449	
	non noble metal	copper	7440-50-8	11.460	9.94	10.19	99446	102048
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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